

## Message Text

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46

ORIGIN EB-07

INFO OCT-01 CIAE-00 COME-00 DODE-00 NSAE-00 TRSE-00 EUR-12

ERDA-05 ISO-00 MC-02 ACDA-05 /032 R

DRAFTED BY EB/ITP/EWT:LROSS:ERS

APPROVED BY EB/ITP/EWT:RWPRACHT

COMMERCE/OEA-RGAREL

RPE

COMMERCE/OEA-CSEASWORD

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R 262312Z MAR 75

FM SECSTATE WASHDC

TO USMISSION OECD PARIS

C O N F I D E N T I A L STATE 068900

EXCON

E.O. 11652: XGDS-1

TAGS: ESTC, COCOM, US, RO

SUBJECT: US THERMOCOMPRESSION BONDER TO ROMANIA -  
IL 1355

REFS: A) COCOM DOC (74)2260  
B) OECD PARIS 30333

1) THE US THERMOCOMPRESSION BONDER IS SUITABLE FOR MAKING  
WIRE BONDS IN HYBRID CIRCUITS AS WELL AS IN THE PRODUCTION  
OF MANY OTHER TYPES OF SEMICONDUCTOR DEVICES. IT IS NOT  
LIMITED TO PRODUCING HYBRID CIRCUITS. IT IS AN OLDER  
TYPE OF BONDER AND IS SIMILAR TO MANY OTHER BONDERS WHICH  
HAVE BEEN APPROVED BY COCOM AS INDIVIDUAL UNITS AND  
CONTAINED IN PLANT PACKAGES TO POLAND AND ROMANIA. THE  
SUBJECT CASE IS FOR ROMANIA.

2) UK QUERY APPARENTLY PROMPTED BY US STATEMENT IN  
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CONNECTION WITH OBJECTION TO UK DOC (74)1901 CASE FOR

HUNGARY. THE US OBJECTED TO THE HUNGARIAN CASE NOT SPECIFICALLY BECAUSE THE BONDER WAS CONSIDERED "FRONT-END EQUIPMENT" BUT BECAUSE THE HYBRID EPOXY DYE BONDER WAS DESIGNED SPECIFICALLY TO MOUNT SILICON CHIPS ON HYBRID CIRCUITS AND HYBRID CIRCUITS ARE USED PRIMARILY FOR MILITARY APPLICATIONS RATHER THAN IN RADIO AND TV SETS AS INDICATED IN THE UK SUBMISSION. IN ADDITION HYBRID EPOXY DYE BONDERS HAVE NOT PREVIOUSLY BEEN APPROVED FOR EXPORT TO ANY COMMUNIST COUNTRY, INCLUDING POLAND AND ROMANIA. KISSINGER

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## Message Attributes

**Automatic Decaptoning:** X  
**Capture Date:** 01 JAN 1994  
**Channel Indicators:** n/a  
**Current Classification:** UNCLASSIFIED  
**Concepts:** EQUIPMENT, STRATEGIC TRADE CONTROLS, EXCEPTIONS LIST  
**Control Number:** n/a  
**Copy:** SINGLE  
**Draft Date:** 26 MAR 1975  
**Decaption Date:** 01 JAN 1960  
**Decaption Note:**  
**Disposition Action:** RELEASED  
**Disposition Approved on Date:**  
**Disposition Authority:** GarlanWA  
**Disposition Case Number:** n/a  
**Disposition Comment:** 25 YEAR REVIEW  
**Disposition Date:** 28 MAY 2004  
**Disposition Event:**  
**Disposition History:** n/a  
**Disposition Reason:**  
**Disposition Remarks:**  
**Document Number:** 1975STATE068900  
**Document Source:** CORE  
**Document Unique ID:** 00  
**Drafter:** LROSS:ERS  
**Enclosure:** n/a  
**Executive Order:** X1  
**Errors:** N/A  
**Film Number:** D750107-0318  
**From:** STATE  
**Handling Restrictions:** n/a  
**Image Path:**  
**ISecure:** 1  
**Legacy Key:** link1975/newtext/t19750312/aaaaakpd.tel  
**Line Count:** 71  
**Locator:** TEXT ON-LINE, ON MICROFILM  
**Office:** ORIGIN EB  
**Original Classification:** CONFIDENTIAL  
**Original Handling Restrictions:** n/a  
**Original Previous Classification:** n/a  
**Original Previous Handling Restrictions:** n/a  
**Page Count:** 2  
**Previous Channel Indicators:** n/a  
**Previous Classification:** CONFIDENTIAL  
**Previous Handling Restrictions:** n/a  
**Reference:** 75 COCOM DOC (7260)  
**Review Action:** RELEASED, APPROVED  
**Review Authority:** GarlanWA  
**Review Comment:** n/a  
**Review Content Flags:**  
**Review Date:** 20 MAY 2003  
**Review Event:**  
**Review Exemptions:** n/a  
**Review History:** RELEASED <20 MAY 2003 by GarlanWA>; APPROVED <30 MAY 2003 by GarlanWA>  
**Review Markings:**

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**Review Media Identifier:**  
**Review Referrals:** n/a  
**Review Release Date:** n/a  
**Review Release Event:** n/a  
**Review Transfer Date:**  
**Review Withdrawn Fields:** n/a  
**Secure:** OPEN  
**Status:** NATIVE  
**Subject:** US THERMOCOMPRESSION BONDER TO ROMANIA - IL 1355  
**TAGS:** ESTC, US, RO, COCOM  
**To:** OECD PARIS  
**Type:** TE  
**Markings:** Margaret P. Grafeld Declassified/Released US Department of State EO Systematic Review 05 JUL 2006